

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	ASSIGNMENT		
CONVEYING PARTY DATA			
	Name	Execution Date	
	Yu-Ying Lin	11/05/2015	
	Chueh-Yang Liu	11/05/2015	
	Yu-Ren Wang	11/05/2015	
	Neng-Hui Yang	11/06/2015	
RECEIVING PARTY DATA			
Name:	UNITED MICROELECTRONICS CORP.		
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park		
City:	Hsin-Chu City		
State/Country:	TAIWAN		
PROPERTY NUMBERS Total: 1			
	Property Type	Number	
	Application Number:	15352528	
CORRESPONDENCE DATA			
Fax Number:	(703)997-4517		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	3027291562		
Email:	Patent.admin.uspto.cr@naipo.com		
Correspondent Name:	WINSTON HSU		
Address Line 1:	P.O.BOX 506		
Address Line 4:	MERRIFIELD, VIRGINIA 22116		
ATTORNEY DOCKET NUMBER:	NAUP2624USA1		
NAME OF SUBMITTER:	SIBYL YU		
SIGNATURE:	/SIBYL YU/		
DATE SIGNED:	11/15/2016		
Total Attachments: 8			
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PATENT

REEL: 040331 FRAME: 0743

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

**SEMICONDUCTOR DEVICE WITH EPITAXIAL STRUCTURE AND
MANUFACTURING METHOD THEREOF**

As the below named inventor, I hereby declare that:

This declaration is directed to:

☒ The attached application, or

☐ United States application number _____ filed on _____, or

☐ PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS** having a postal address of **CORP.**

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this **NOV 05 2015** (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yu-Ying Lin**

Date: 2015/11/5

Signature: Yu-Ying Lin

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chueh-Yang Liu**

Date:

2015/11/5

Signature:

Chueh-Yang Liu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yu-Ren Wang**

Date: 11/5 NOV 05 2015

Signature: Yu Ren Wang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Neng-Hui Yang**

Date:

11/6/2015

Signature:

Neng-Hui Yang